Product data sheet

1 Product profile

1.1 General description

Two planar PIN diodes in series configuration in an SOT23 small plastic SMD package.

1.2 Features and benefits

- Two elements in series configuration in a small-sized plastic SMD package
- · Low diode capacitance
- · Low diode forward resistance

1.3 Applications

General RF application



General purpose PIN diode

2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode		
2	cathode	3	3
3	common connection	1 2 Top view	1 2 aaa-025249

3 Ordering information

Table 2. Ordering information

Type number Package			
	Name	Description	Version
BAP50-04	-	plastic surface-mounted package; 3 leads	SOT23

4 Marking

Table 3. Marking code

Type number	Marking code
BAP50-04	4L%

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	50	V
I _F	forward current		-	50	mA
P _{tot}	total power dissipation	T _{sp} ≤ 90 °C	-	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-sp)}	thermal resistance from junction to solder point		220	K/W

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7 Characteristics

Table 6. Characteristics

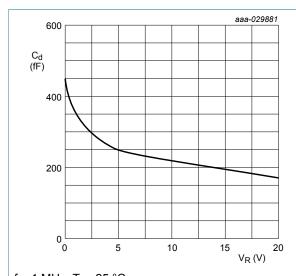
 T_i = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _F	forward voltage	I _F = 50 mA		-	0.95	1.1	V
V _R	reverse voltage	I _R = 10 μA		50	-	-	V
I _R	reverse current	V _R = 50 V		-	-	100	nA
C _d	diode capacitance	f = 1 MHz (see <u>Figure 1</u>)					
		V _R = 0 V		-	0.45	-	pF
		V _R = 1 V		-	0.35	0.6	pF
		V _R = 5 V		-	0.3	0.5	pF
r _D	diode forward resistance	ance f = 100 MHz (see <u>Figure 2</u>)					
		I _F = 0.5 mA	[1]	-	25	40	Ω
		I _F = 1 mA	[1]	-	14	25	Ω
		I _F = 10 mA	[1]	-	3	5	Ω
τL	charge carrier life time	when switched from I_F = 10 mA to I_R 6 mA; R_L = 100 W; measured at I_R 3 mA		-	1.05	-	μs
L _S	series inductance			-	1.4	-	nH

^[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

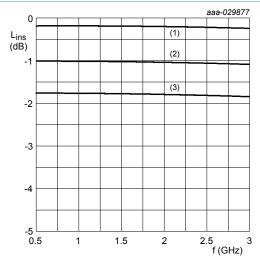
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8 Graphical data



 $f = 1 \text{ MHz}; T_j = 25 ^{\circ}\text{C}.$

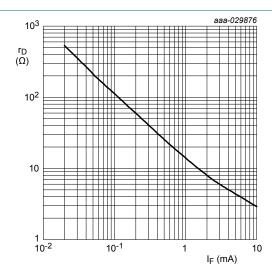
Figure 1. Diode capacitance as a function of reverse voltage (typical values)



Diode inserted in series with a 50 Ω strip line circuit and biased via the analyzer T-network. T_{amb} = 25 °C.

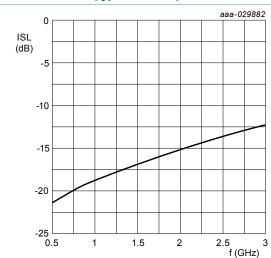
- (1) $I_F = 10 \text{ mA}$
- (2) $I_F = 1 \text{ mA}$
- (3) $I_F = 0.5 \text{ mA}$

Figure 3. Insertion loss of the diode as a function of frequency (typical values)



 $f = 100 \text{ MHz}; T_i = 25 ^{\circ}\text{C}.$

Figure 2. Diode forward resistance as a function of forward current (typical values)

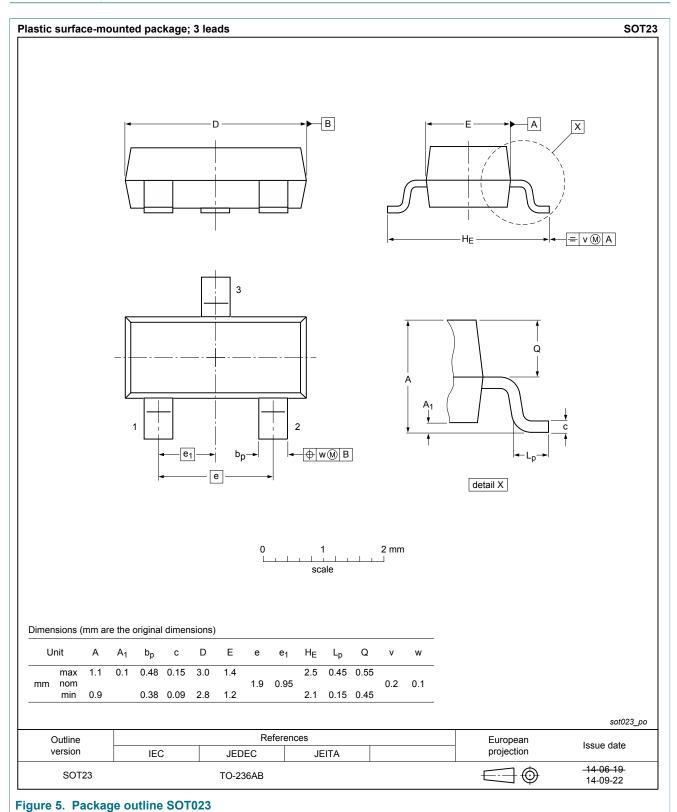


Diode zero biased and inserted in series with a 50 Ω strip line circuit. T_{amb} = 25 $^{\circ}C.$

Figure 4. Isolation of the diode as a function of frequency (typical values)

General purpose PIN diode

9 Package outline



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10 Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	acceptable quality level
PIN	P-type, intrinsic, N-type
RF	radio frequency
S4	special inspection level 4
SMD	surface-mounted device

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
BAP50-04 v.3	AP50-04 v.3 20181126 Product data sheet - BAP50-				
Modifications:	 Section 1.2 "Features and benefits" has been updated. The "Legal information" pages have been updated. 				
BAP50-04 v .2.1	19991203	Product data sheet	-	BAP50-04 v.1	

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12 Legal information

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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